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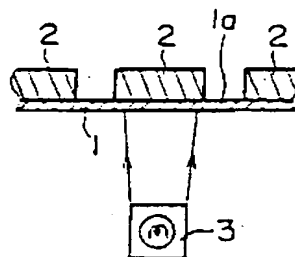
APPLICATION DATE : 08-12-89
APPLICATION NUMBER : 01319327

APPLICANT : SUMITOMO ELECTRIC IND LTD;

INVENTOR : NISHIGUCHI KATSUNORI;

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TITLE : METHOD FOR PICKING UP
SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To prevent the decrease in adhesion of an adhesive layer to which neighboring semiconductor devices are fixed by projecting ultraviolet rays on every semiconductor device, and weakening only the adhesion of the adhesive layer for fixing the semiconductor device.

CONSTITUTION: An adhesive layer is formed of an adhesive material whose adhesion is decreased when ultraviolet rays are projected. The adhesive layer is formed on a surface 1a of expanded tape 1. A plurality of semiconductor devices (chip) 2 are bonded and fixed on the adhesive layer. When the chip 2 is released from the expanded tape 1, ultraviolet rays are projected on the adhesive layer through the rear side of the expanded tape 1 with an ultraviolet-ray projecting means 3, and the adhesion of the adhesive layer is decreased. At this time, the ultraviolet rays are projected on every part to which the chip 2 is fixed for several seconds. Every chip 2 which is fixed to the adhesive layer at the part where the adhesion is decreased by the projection of the ultraviolet rays is released from the expanded tape 1. In this way, the remaining semiconductor device can be preserved under the intact state wherein the device is bonded to the part with the rigid adhesion.

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